

Hyperfast Rectifier, 20 A FRED Pt® G5



LINKS TO ADDITIONAL RESOURCES







PRIMARY CHARACTERISTICS						
$I_{F(AV)}$	20 A					
V_{R}	1200 V					
V _F at I _F at 125 °C	2.40 V					
t _{rr}	29 ns					
T _J max.	175 °C					
Package	D ² PAK 2L (TO-263AB 2L)					
Circuit configuration	Single					

FEATURES

Hyperfast and optimized Q_{rr}



 Best in class forward voltage drop and switching losses trade off

COMPLIANT HALOGEN **FREE**

Optimized for high speed operation

- 175 °C maximum operating junction temperature
- Polyimide passivation
- Meets MSL level 1, per J-STD-020, LF maximum peak of 245 °C
- Designed and qualified according to JEDEC®-JESD 47
- Material categorization: for definitions of compliance please see www.vishav.com/doc?99912

DESCRIPTION / APPLICATIONS

Featuring a unique combination of low conduction and switching losses, this rectifier is the right choice for high frequency converters, both soft switched / resonant. Specifically designed to improve efficiency of PFC and output rectification stages of EV / HEV battery charging stations, booster stage of solar inverters and UPS applications, these devices are perfectly matched to operate with MOSFETs or high speed IGBTs.

MECHANICAL DATA

Case: D²PAK 2L (TO-263AB 2L)

Molding compound meets UL 94 V-0 flammability rating

Terminals: matte tin plated leads, solderable per

J-STD-002

ABSOLUTE MAXIMUM RATINGS								
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS				
Repetitive peak reverse voltage	V_{RRM}		1200	V				
Average rectified forward current	I _{F(AV)}	T _C = 88 °C	20					
Repetitive peak forward current	I _{FRM}	T _C = 88 °C, D = 0.50, f = 20 kHz	33	Α				
Non-repetitive peak surge current	I _{FSM}	$T_C = 45$ °C, $t_p = 10$ ms, sine wave	110					
Operating junction and storage temperature	T_J , T_{Stg}		-55 to +175	°C				

ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified)								
PARAMETER	SYMBOL	L TEST CONDITIONS MIN. TYP. M			MAX.	UNITS		
Breakdown voltage, blocking voltage	V_{BR} , V_{R}	I _R = 100 μA	1200	-	-	.,		
Forward voltage	V _F	I _F = 20 A	-	2.71	3.6	V		
		I _F = 20 A, T _J = 125 °C	-	2.40	-			
Payaraa laakaga aurrant	I _R	$V_R = V_R$ rated	-	-	50			
Reverse leakage current		$T_J = 125$ °C, $V_R = V_R$ rated	-	-	500	μA 000		
Junction capacitance	C _T	V _R = 200 V	-	10	-	pF		
Series inductance	L _S	Measured to lead 5 mm from package body	-	8	-	nH		



DYNAMIC RECOVERY CHARACTERISTICS (T _J = 25 °C unless otherwise specified)								
PARAMETER	SYMBOL	TEST	MIN.	TYP.	MAX.	UNITS		
		$I_F = 1.0 \text{ A}, dI_F/dI_F$	$It = 100 \text{ A/}\mu\text{s}, V_R = 30 \text{ V}$	1	29	-		
Reverse recovery time	t _{rr}	T _J = 25 °C		-	115	-	ns	
		T _J = 125 °C		ı	170	-	115	
Peak recovery current	1	T _J = 25 °C	I _F = 12 A dI _F /dt = 600 A/μs	ı	10	-	А	
reak recovery current	I _{RRM}	T _J = 125 °C	V _R = 400 V	-	16	-		
Poverne receivent charge	Q _{rr}	T _J = 25 °C		-	430	-	nC	
Reverse recovery charge		T _J = 125 °C		1	1045	-		
Reverse recovery time	+	T _J = 25 °C		-	93	-	ns	
neverse recovery time	t _{rr}	T _J = 125 °C		-	122	-		
Dook recovery ourrent		T _J = 25 °C	$I_F = 20 \text{ A}$	-	21		А	
Peak recovery current	I _{RRM}	T _J = 125 °C	dl _F /dt = 1000 A/μs V _R = 800 V	-	32		_ ^	
Poverne receivent charge	Q _{rr}	T _J = 25 °C		-	850	-	nC	
Reverse recovery charge		T _J = 125 °C		-	2020	-		

THERMAL - MECHANICAL SPECIFICATIONS								
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS		
Thermal resistance, junction-to-case	R _{thJC}		-	-	1.7	°C/W		
Weight			-	2.0	-	g		
Maximum junction and storage temperature range	T _J , T _{Stg}		-55	-	175	°C		
Marking device		Case style D ² PAK 2L (TO-263AB 2L)	_) E5TX2112S					

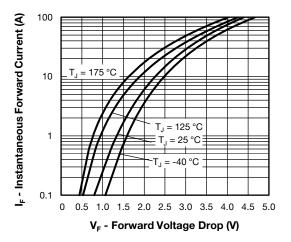


Fig. 1 - Forward Voltage Drop Characteristics

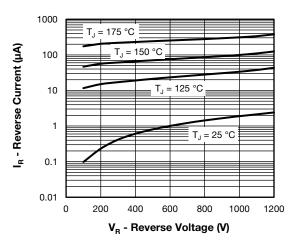


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

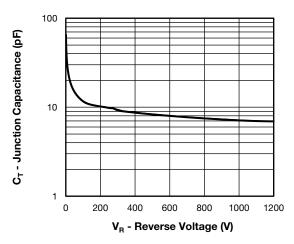


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

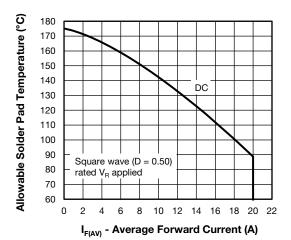


Fig. 4 - Maximum Allowable Case Temperature vs.
Average Forward Current

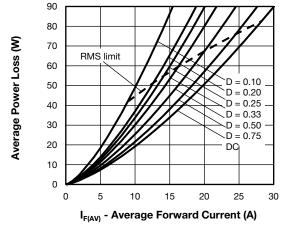


Fig. 5 - Forward Power Loss Characteristics

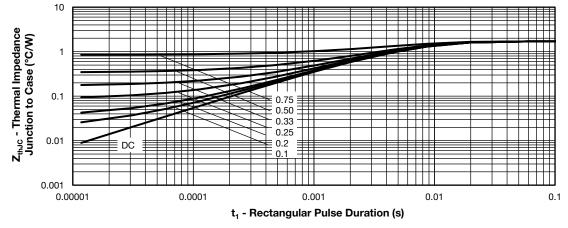


Fig. 6 - Transient Thermal Impedance, Junction to Case

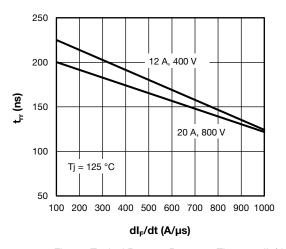


Fig. 7 - Typical Reverse Recovery Time vs. dl_F/dt

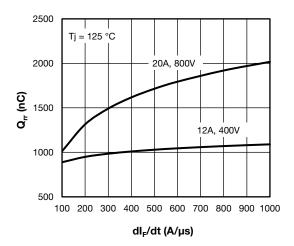


Fig. 8 - Typical Stored Charge vs. dl_F/dt

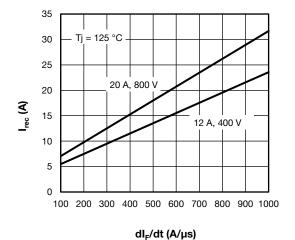


Fig. 9 - Typical Stored Charge vs. dl_F/dt

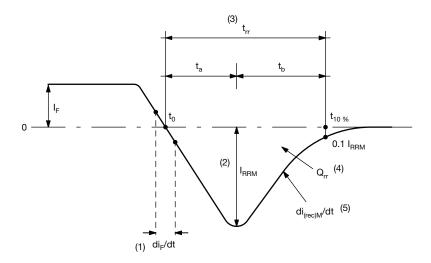


Fig. 10 - Reverse Recovery Waveform and Definitions

Notes

- $^{(1)}$ di_F/dt rate of change of current through zero crossing
- (2) I_{RRM} peak reverse recovery current
- $^{(3)}$ t_{rr} reverse recovery time measured from t₀, crossing point of negative going I_F, to point t_{10%}, 0.1 I_{RRM}
- $^{(4)}~Q_{rr}$ area under curve defined by t_0 and $t_{10~\%}$

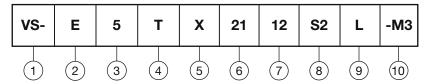
$$Q_{rr} = \int_{t_0}^{t_{10}\%} I(t)dt$$

 $^{(5)}$ $di_{(rec)}M/dt$ - peak rate of change of current during t_{b} portion of t_{rr}



ORDERING INFORMATION TABLE

Device code



1 - Vishay Semiconductors product

- E = single diode

3 - 5 = FRED generation 5

4 - Package:

 $T = TO-263 / D^2PAK package$

5 - X = hyperfast recovery

6 - Current rating (21 = 20 A)

7 - Voltage rating (12 = 1200 V)

8 - S2 = true 2 pin D^2PAK

9 - None = tube (50 pieces)

• L = tape and reel (left oriented, for D²PAK package)

If needed different orientation/packaging, please contact factory

- Environmental digit:

-M3 = halogen-free, RoHS-compliant, and termination lead (Pb)-free

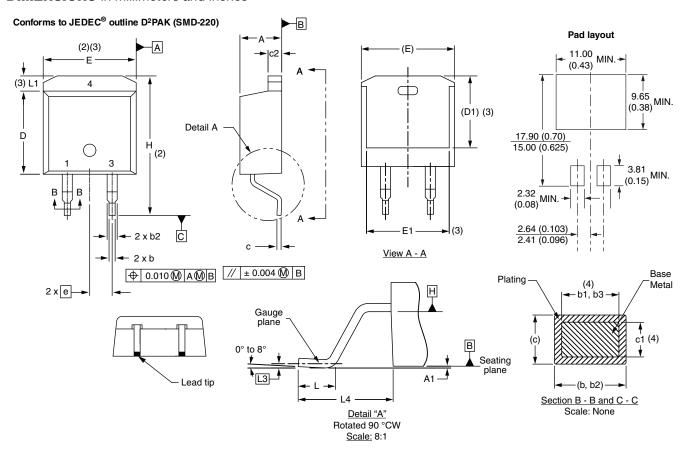
ORDERING INFORMATION (Example)							
PREFERRED P/N	BASE QUANTITY	PACKAGING DESCRIPTION					
VS-E5TX2112S2L-M3	800	13" diameter reel					

LINKS TO RELATED DOCUMENTS					
Dimensions	www.vishay.com/doc?96683				
Part marking information	www.vishay.com/doc?96693				
Packaging information	www.vishay.com/doc?95032				
SPICE Model	www.vishay.com/doc?97159				



D²PAK 2L (TO-263AB 2L)

DIMENSIONS in millimeters and inches



SYMBOL	MILLIM	IETERS	INCHES MIN. MAX.		NOTES
STIVIBUL	MIN.	MAX.			NOTES
Α	4.06	4.83	0.160	0.190	
A1	0.00	0.254	0.000	0.010	
b	0.51	0.99	0.020	0.039	
b1	0.51	0.89	0.020	0.035	4
b2	1.14	1.78	0.045	0.070	
b3	1.14	1.73	0.045	0.068	4
С	0.38	0.74	0.015	0.029	
c1	0.38	0.58	0.015	0.023	4
c2	1.14	1.65	0.045	0.065	
D	8.51	9.65	0.335	0.380	2

SYMBOL	MILLIM	ETERS	INCHES		NOTES
STWIBOL	MIN.	MAX.	MIN.	MAX.	NOTES
D1	6.86	8.00	0.270	0.315	3
E	9.65	10.67	0.380	0.420	2, 3
E1	7.90	8.80	0.311	0.346	3
е	2.54	2.54 BSC		0.100 BSC	
Н	14.61	15.88	0.575	0.625	
L	1.78	2.79	0.070	0.110	
L1	-	1.65	-	0.066	3
L3	0.25 BSC		0.010	BSC	
L4	4.78	5.28	0.188	0.208	

Notes

- (1) Dimensioning and tolerancing per ASME Y14.5 M-1994
- (2) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body
- (3) Thermal pad contour optional within dimension E, L1, D1 and E1
- (4) Dimension b1 and c1 apply to base metal only
- (5) Datum A and B to be determined at datum plane H
- (6) Controlling dimension: inch
- (7) Outline conforms to JEDEC® outline TO-263AB



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